

# Platform Working Group

15 December 2011

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# Status Report

- First meeting held on February 24<sup>th</sup> (Teleconference)
  - 12 attendees
- Set 9 month timeframe for completion.
- Assumes Monthly teleconference with Face-to-Face meeting in summer and at AutoTestCon
- Agreed to data gathering approach and Leads
  - PXI – Mike Dewey (Geotest)
  - LXI – John Stratton (temporary)(Agilent)
  - AXIe – Von Campbell (Agilent)
  - VXI - Mike McGoldrick/Peter Hansen (Teradyne)

# Next Steps

- **Finalize Platform data to be gathered.**
  - Application and use of each standard or approach throughout the automatic test industry
  - The IEEE and industry standards that each implements
  - Advantages and weaknesses of each
  - Features of each including scalability, modularity, bus speeds, frequency ranges, power, etc
  - Relative cost of implementation
  - Physical dimensions of chassis and modules; number of slots available
  - Electrical and mechanical requirements
  - Availability of products that use the standard or approach
  - Market trends (growing or declining market shares); outlook for the future of the standard or approach
  - Understanding the Supply Chain (Which Vendors support the different standards)
  - Hybrid System Support (for quite some time there will be few single platform test systems. How does the architecture effect the use in a multi platform system)
- **Platform Leads will assign members to gather data.**

# Criteria

- Test systems are based on standardized architectures - the standards are either managed by consortiums or professional groups - i.e. IEEE, etc.
- Required life cycle for the test system - this will potentially influence design and implementation of the test system(s)
- Test system footprint -depending on the application could be a very key attribute
- Card modular - not to be confused with "modular" which is a term that is used very loosely and broadly by T&M vendors. A card modular architecture will be a consideration if test system density / footprint is a key factor for consideration.
- Test system throughput - this has many ramifications on a test system's architecture including the test system's control bus, the need for distributed processing, support for real-time processes, and even the system's software.
- Requirement to support legacy test systems and programs. This attribute can have a significant effect on a test system's architecture.



## Criteria (Cont)

- Module Size(s)
- Card Cage(s) : Ht/Width/Depth
- Maximum(Theoretical)/Optimum(Achievable) Bus Speeds
- Bus Latency
- EMC Regulatory Requirements per modular standard
- Module Shielding requirements
- Module Spacing
- Module /card cage cooling requirements
- Power requirements(bus voltage rails/power consumption)
- Maximum allowable power consumption per module



## Criteria (Cont)

- Method of Interfacing modules to the target UUT(i.e., Patch Panel, etc.)
- Current market size
- Compound Annual Growth rate(CAGR)
- Supply Chain: Number of Vendors
- Type(Digital,RF,Switching,etc.) and number of products